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(12) **United States Design Patent**
Nagase et al.

(10) **Patent No.: US D443,253 S**

(45) **Date of Patent: ** Jun. 5, 2001**

(54) **TRANSISTOR SUBSTRATE**

(57) **CLAIM**

(75) Inventors: **Toshiaki Nagase; Jun Ishikawa**, both of Kariya (JP)

The ornamental design for a transistor substrate, as shown and described.

(73) Assignee: **Kabushiki Kaisha Toyoda Jidoshokki Seisakusho**, Kariya (JP)

DESCRIPTION

(**) Term: **14 Years**

FIG. 1 is a front elevational view showing a transistor substrate according to a first embodiment of the present invention;

(21) Appl. No.: **29/116,954**

FIG. 2 is a rear elevational view of the substrate of FIG. 1;

(22) Filed: **Jan. 13, 2000**

FIG. 3 is a top plan view of the substrate of FIG. 1;

(30) **Foreign Application Priority Data**

Jul. 14, 1999	(JP)	11-18961
Jul. 14, 1999	(JP)	11-18962
Jul. 14, 1999	(JP)	11-18963
Jul. 14, 1999	(JP)	11-18964

FIG. 4 is a bottom plan view of the substrate of FIG. 1;

FIG. 5 is a right side elevational view of the substrate of FIG. 1, the left side elevational view being a mirror image of the right side elevational view;

(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/182, 184, D13/199; 257/48, 690, 692, 693, 697; 361/395; 324/158.1

FIG. 6 is a top front perspective view of the substrate of FIG. 1;

FIG. 7 is a top plan view showing a transistor substrate according to a second embodiment of the present invention, wherein the front elevational view, the rear elevational view, the bottom plan view, the right side elevational view and the left side elevational view are identical with those of the first embodiment;

FIG. 8 is a top front perspective view of the substrate of FIG. 7;

(56) **References Cited**

U.S. PATENT DOCUMENTS

D. 318,271	*	7/1991	Hasegawa et al.	D13/182
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5,156,983	*	10/1992	Schlesinger et al.	324/158.1 X

FIG. 9 is a top plan view showing a transistor substrate according to a third embodiment of the present invention, wherein the front elevational view, the rear elevational view, the bottom plan view, the right side elevational view and the left side elevational view are identical with those of the first embodiment;

FIG. 10 is a top front perspective view of the substrate of FIG. 9;

FIG. 11 is a top plan view showing a transistor substrate according to a fourth embodiment of the present invention, wherein the front elevational view, the rear elevational view, the bottom plan view, the right side elevational view and the left side elevational view are identical with those of the first embodiment; and,

FIG. 12 is a top front perspective view of the substrate of FIG. 11.

* cited by examiner

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1 Claim, 5 Drawing Sheets

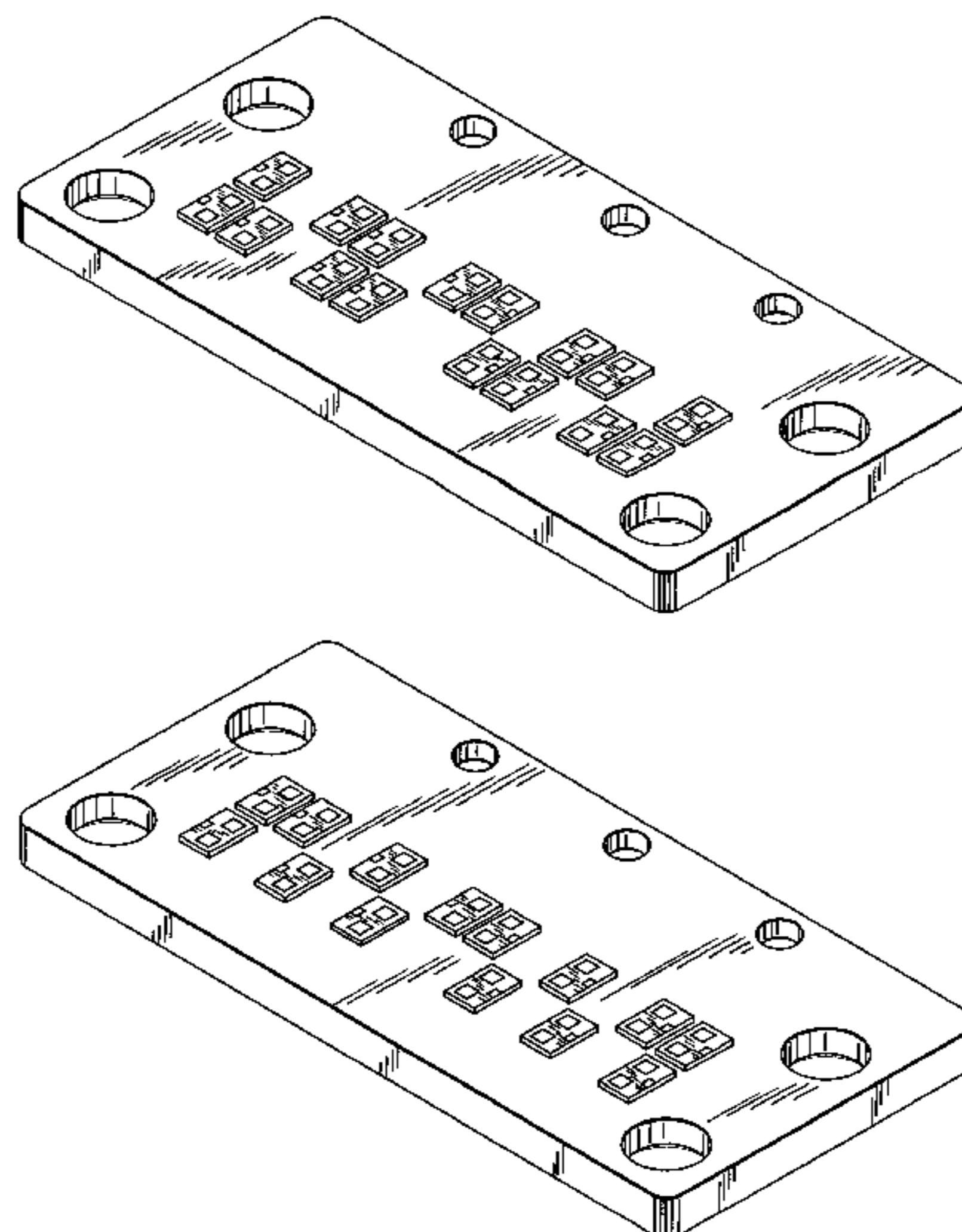




FIG. 1



FIG. 2

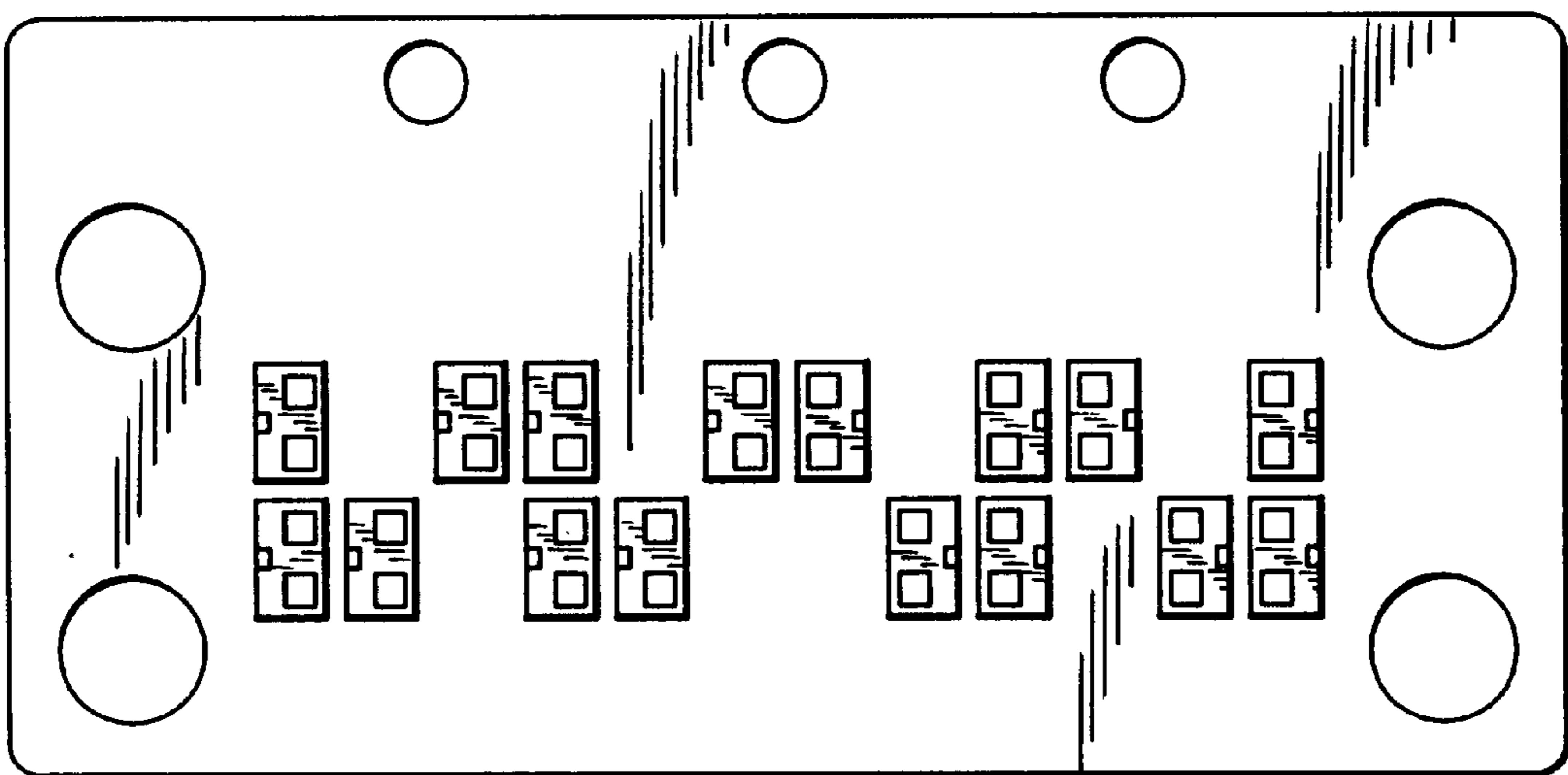


FIG. 3

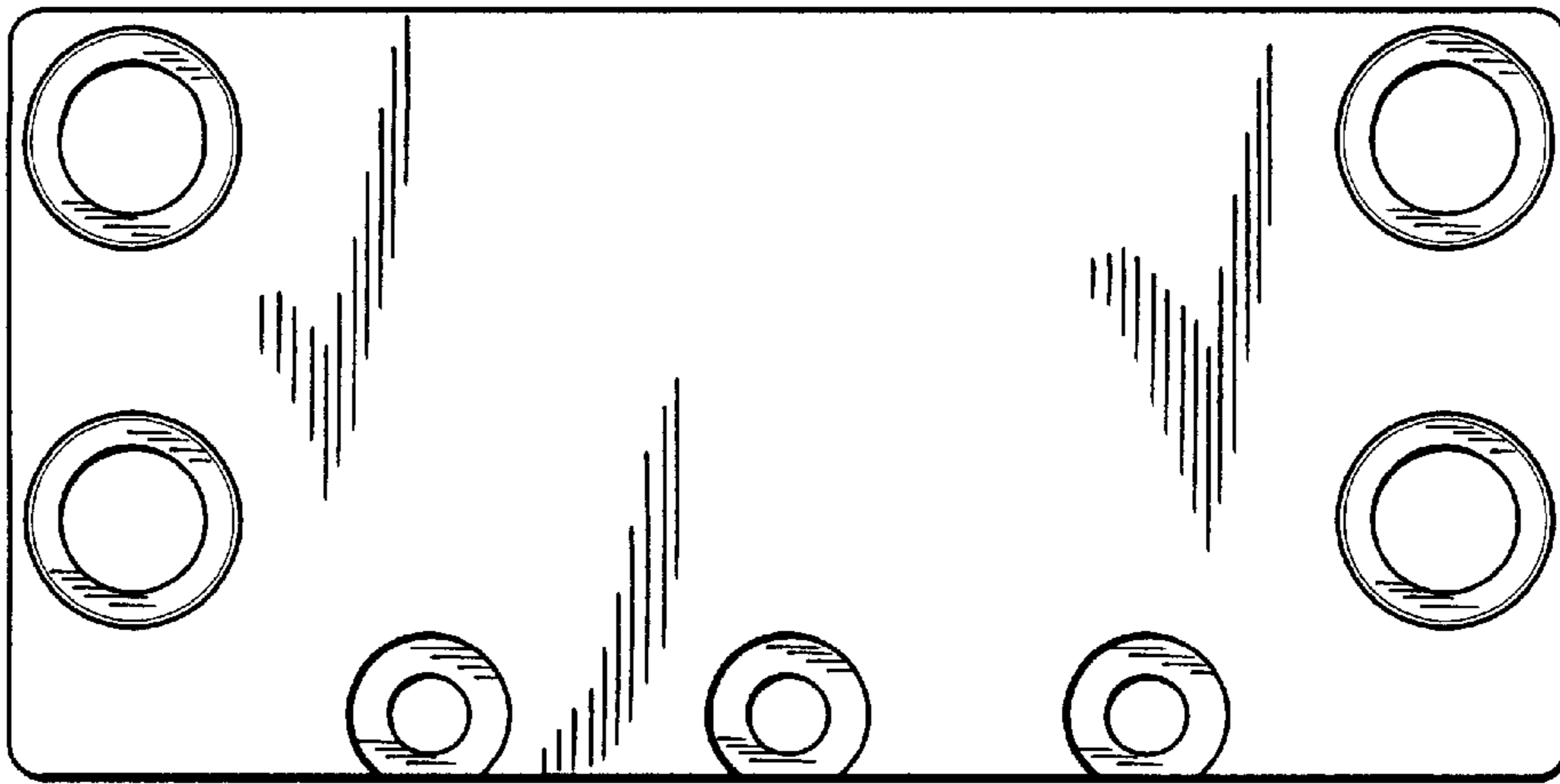


FIG. 4

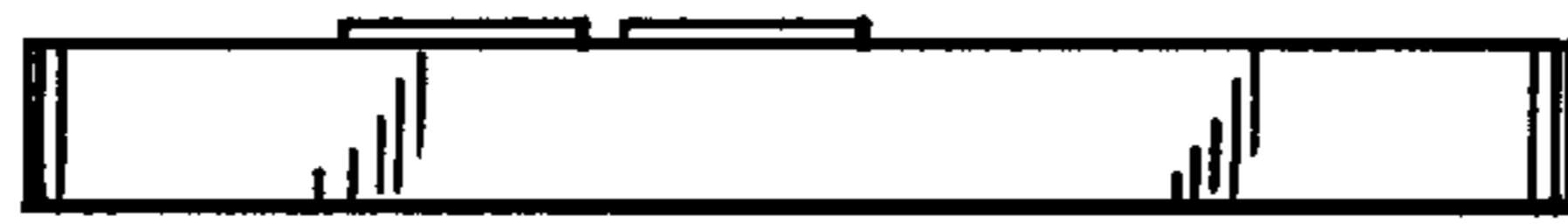


FIG. 5

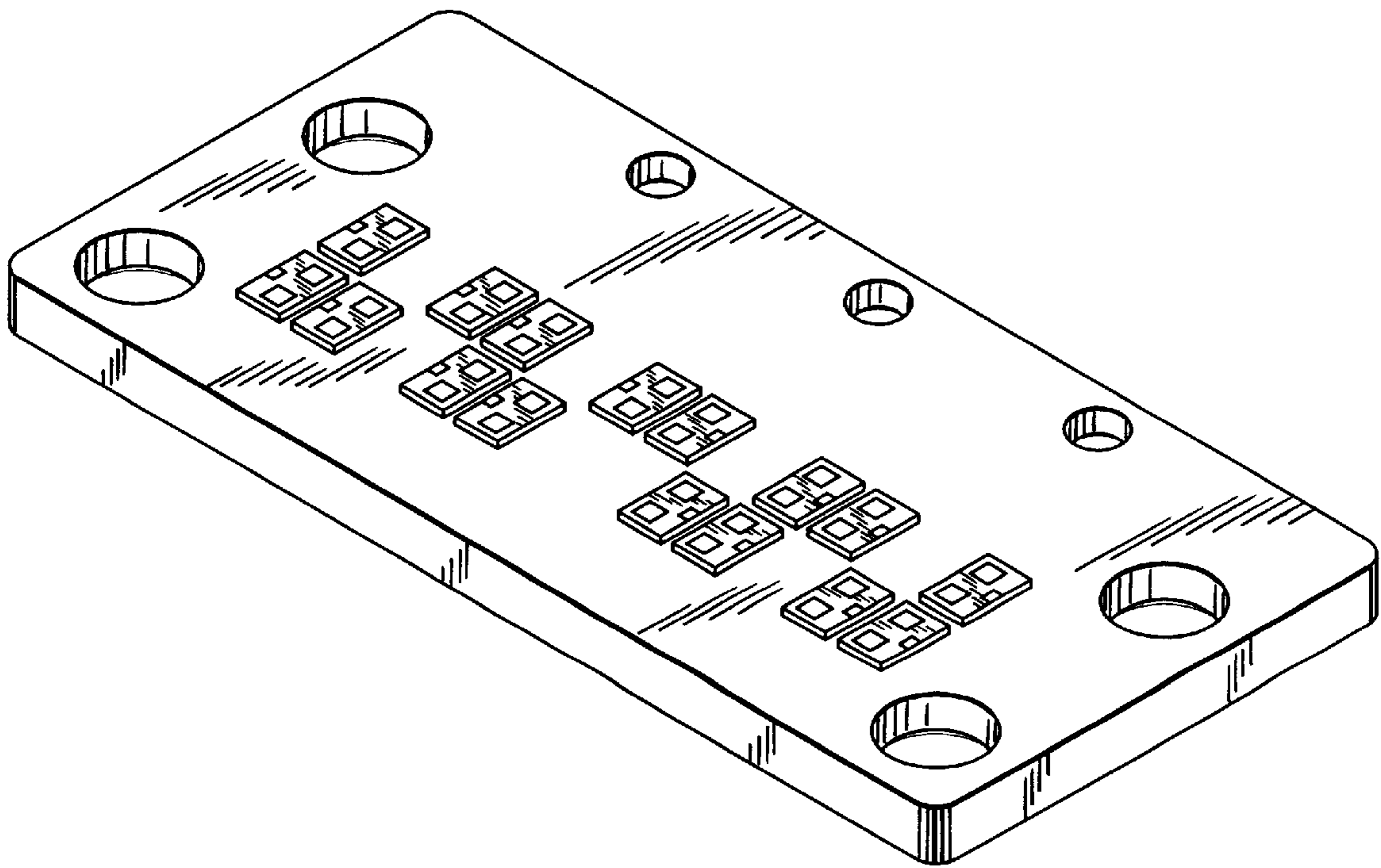


FIG. 6

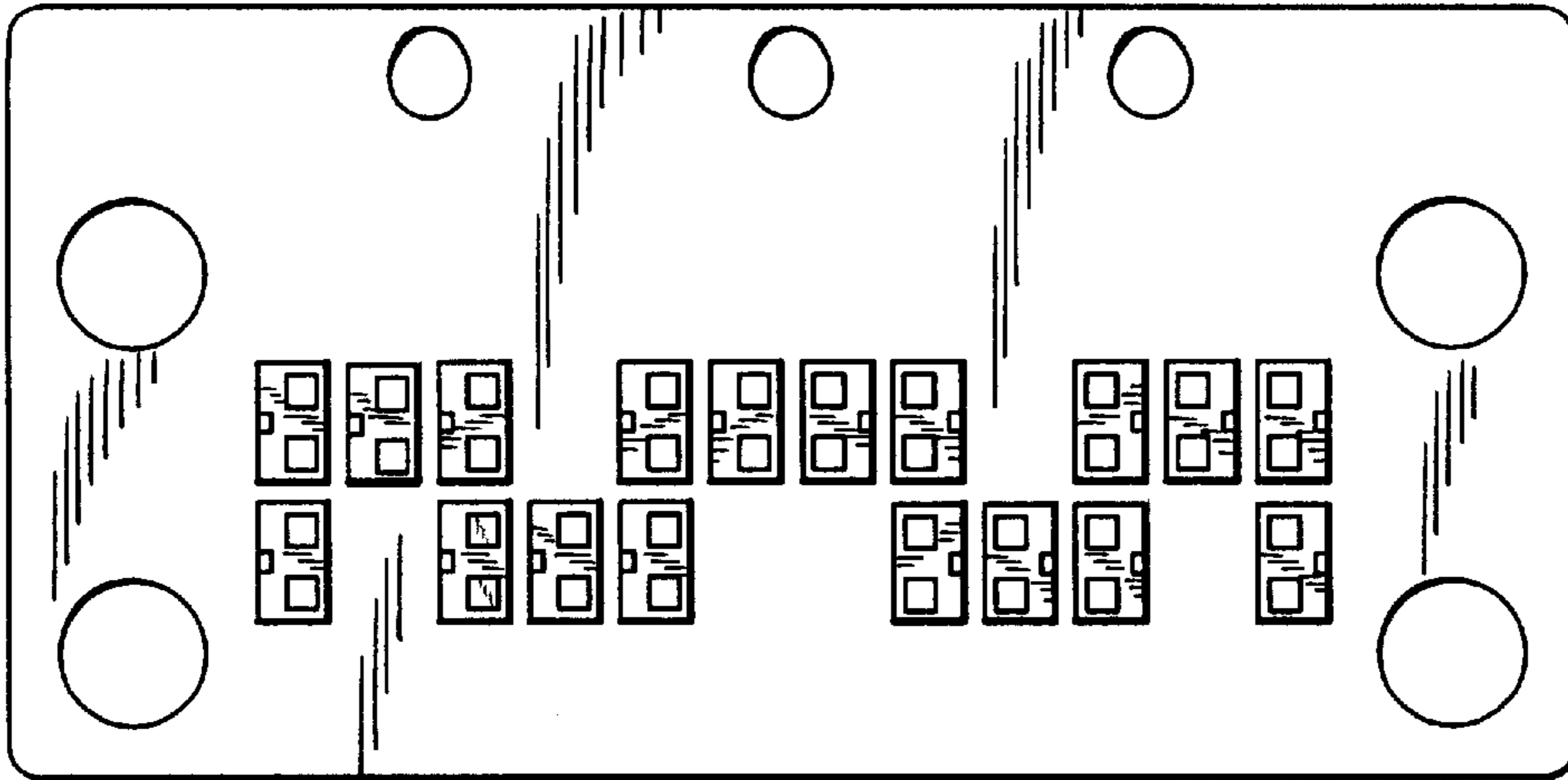


FIG. 7

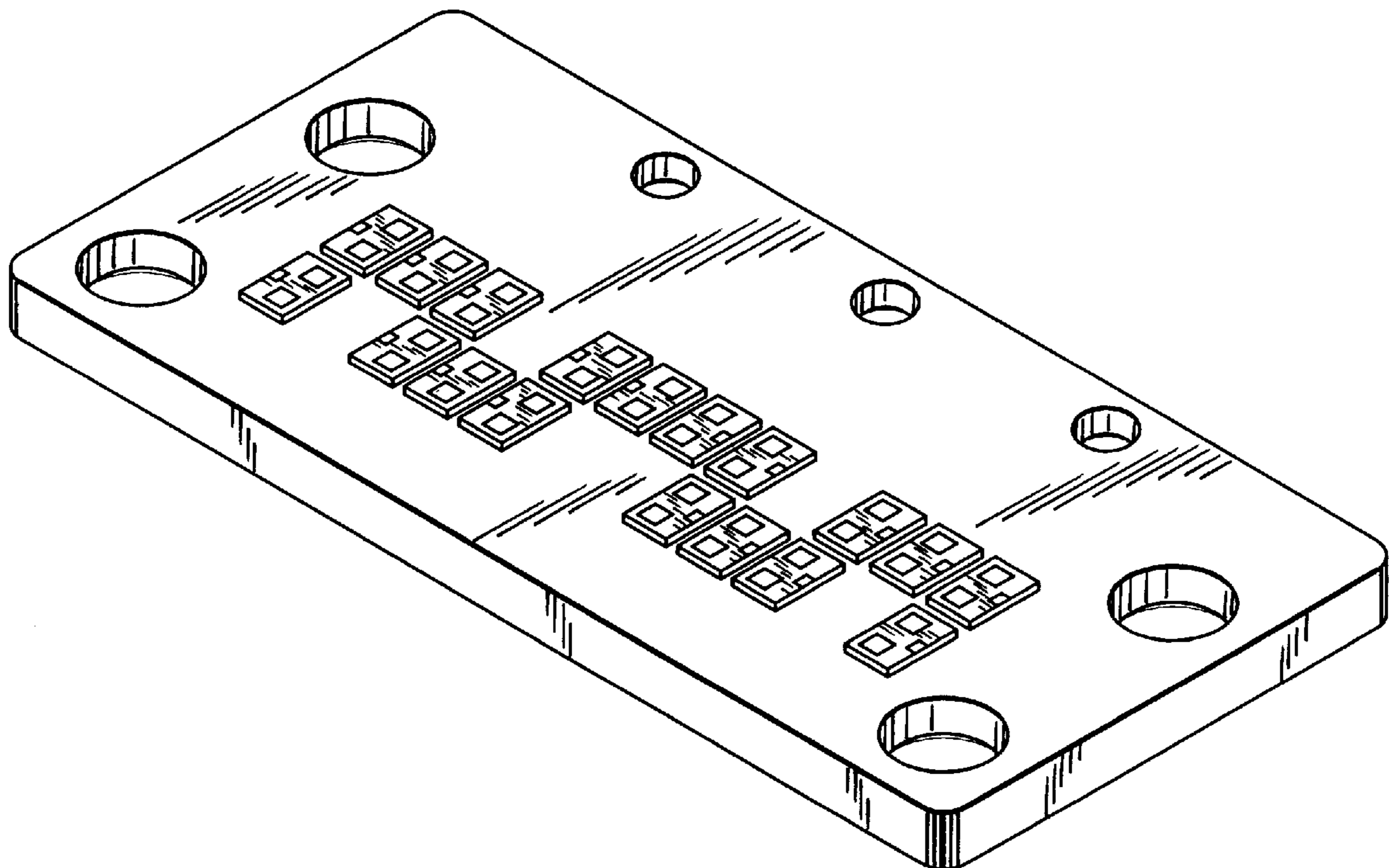


FIG. 8

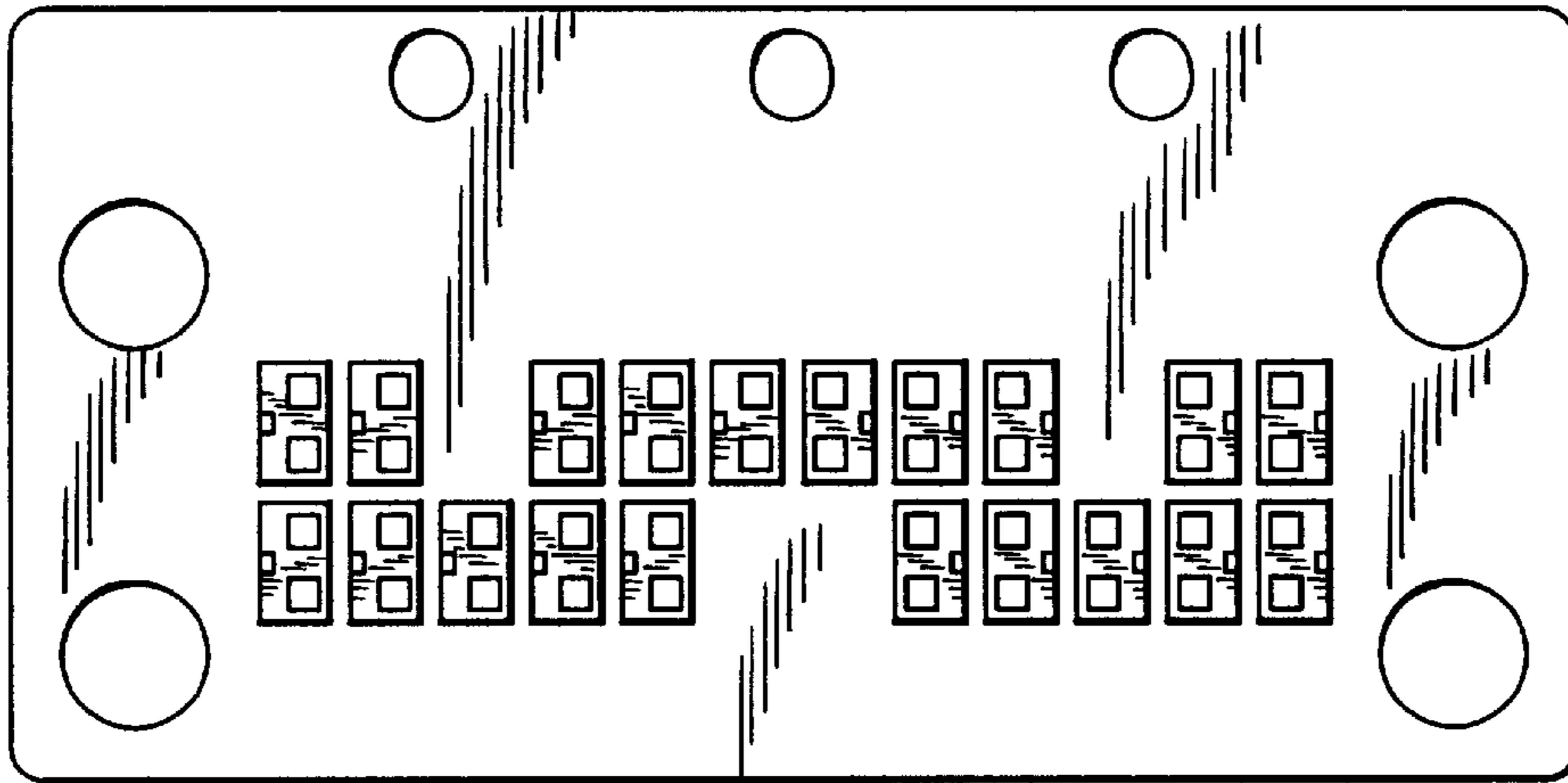


FIG. 9

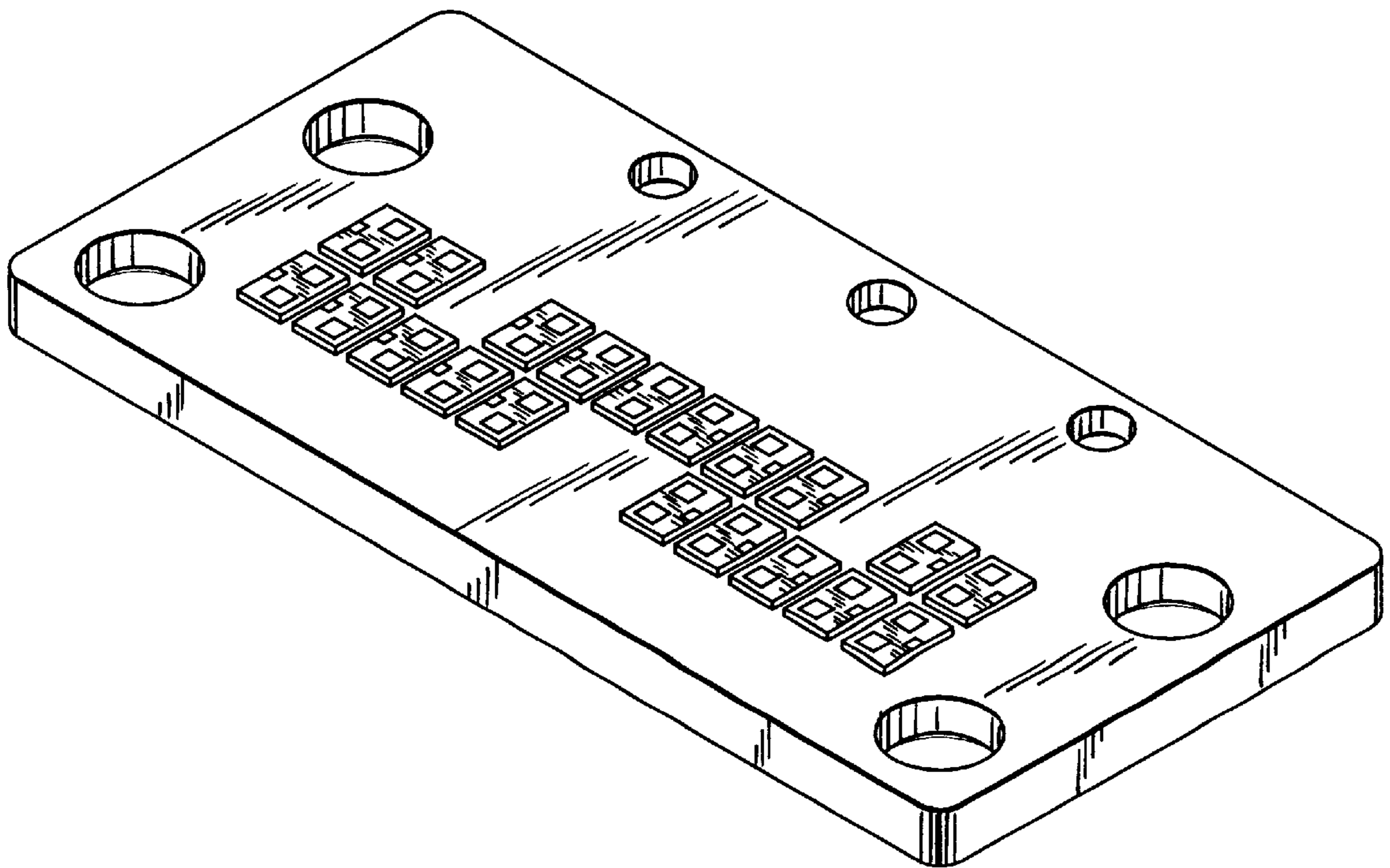


FIG. 10

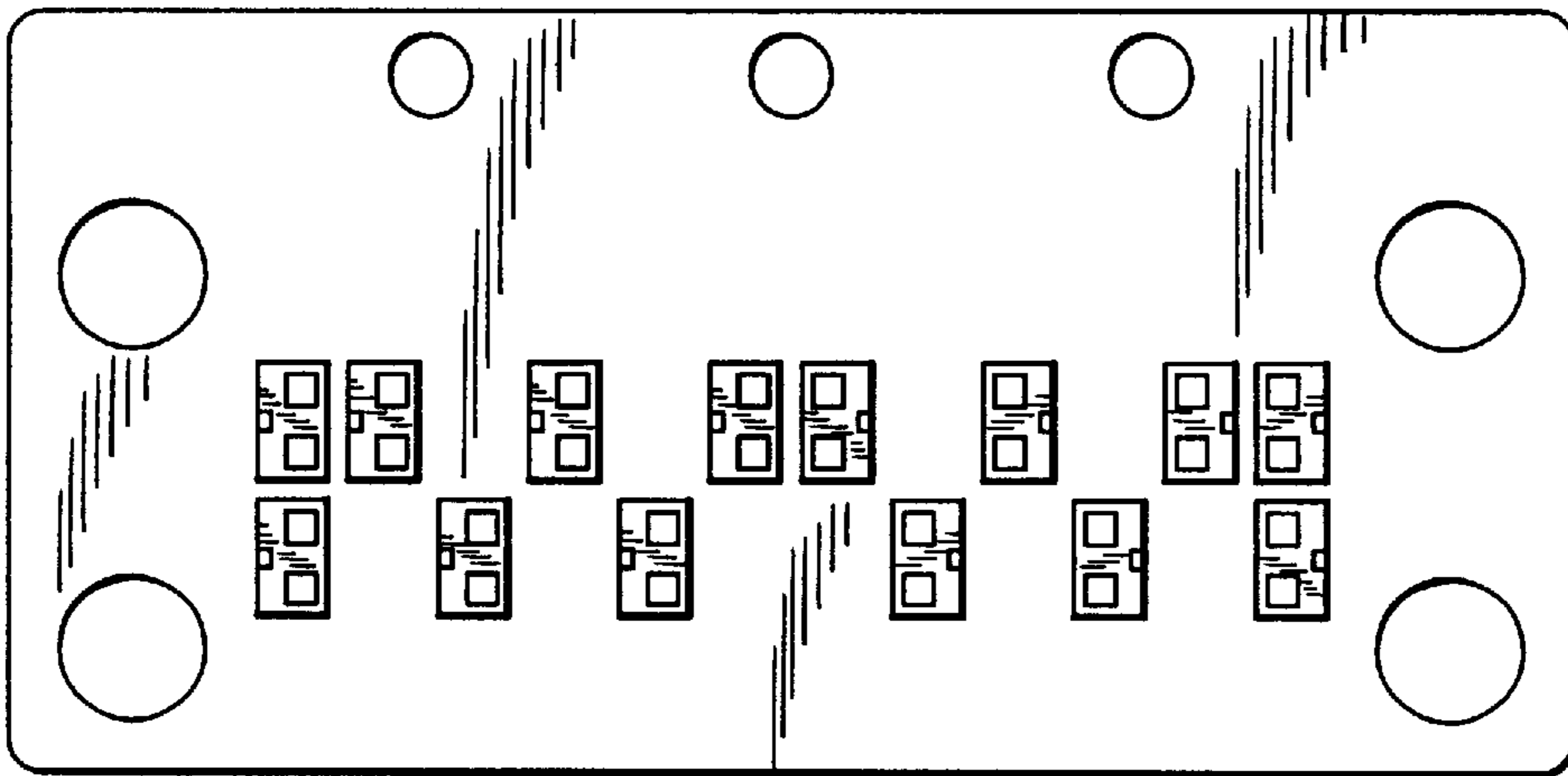


FIG. 11

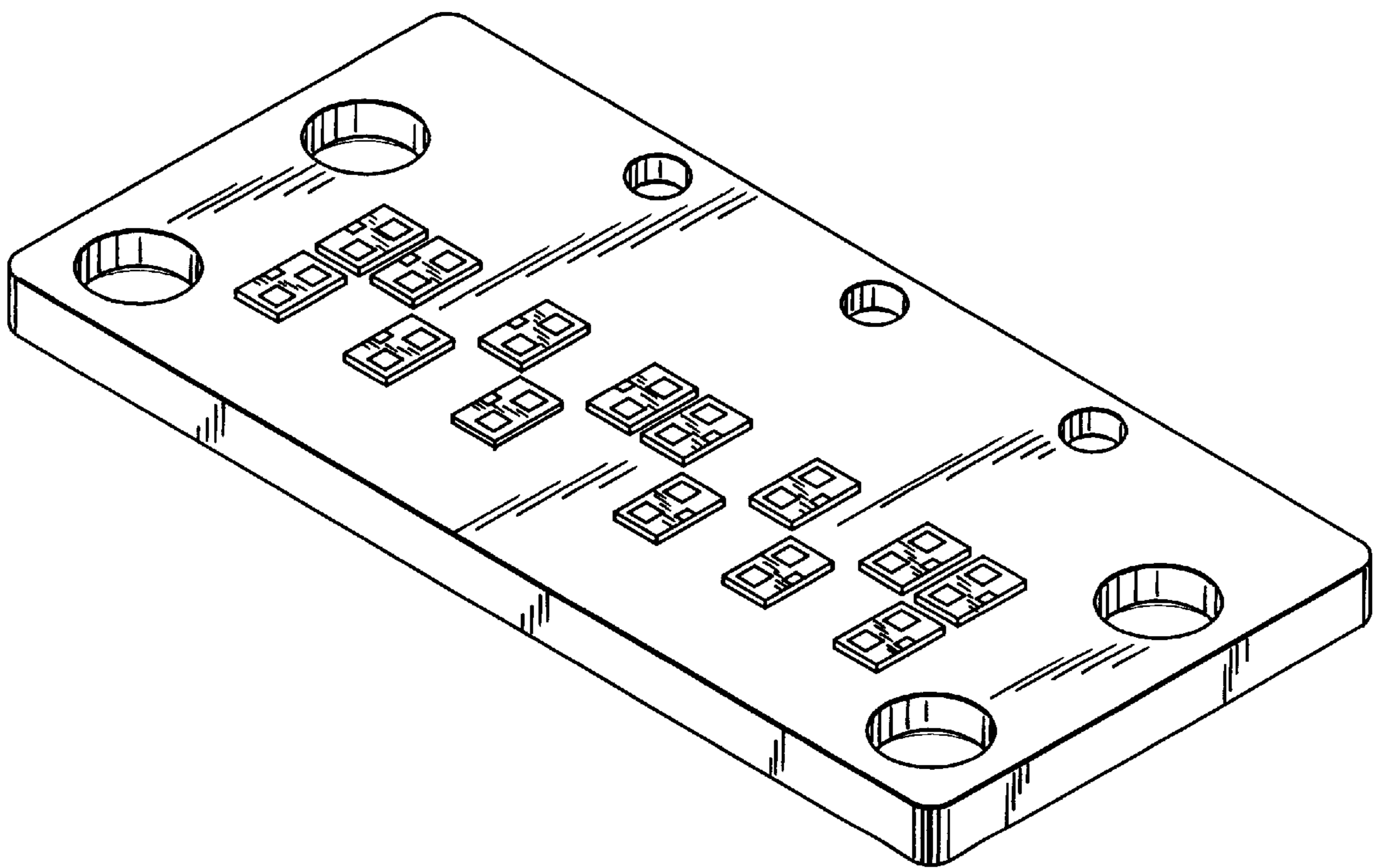


FIG. 12